


**PRODUCT / PROCESS CHANGE INFORMATION**

**1. PCI basic data**

|                      |  |                                      |
|----------------------|--|--------------------------------------|
| 1.1 Company          |                     | STMicroelectronics International N.V |
| 1.2 PCI No.          | AMS/21/13067   |                                      |
| 1.3 Title of PCI     | Test site transfer from Amkor ATT3 to Amkor ATT6 for STBC02 and STBC03 devices in Flip Chip Package. |                                      |
| 1.4 Product Category | see Products List  |                                      |
| 1.5 Issue date       | 2021-10-14   |                                      |

**2. PCI Team**

|                                  |                         |
|----------------------------------|-------------------------|
| <b>2.1 Contact supplier</b>      |                         |
| 2.1.1 Name                       | NEMETH KRISZTINA        |
| 2.1.2 Phone                      | +49 89460062210         |
| 2.1.3 Email                      | krisztina.nemeth@st.com |
| <b>2.2 Change responsibility</b> |                         |
| 2.2.1 Product Manager            | Marcello SAN BIAGIO     |
| 2.1.2 Marketing Manager          | Salvatore DI VINCENZO   |
| 2.1.3 Quality Manager            | Giuseppe LISI           |

**3. Change**

|                     |   |                                   |
|---------------------|---|-----------------------------------|
| <b>3.1 Category</b> | <b>3.2 Type of change</b>   | <b>3.3 Manufacturing Location</b> |
| Transfer            | Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Testing (SOP 2617) | Amkor Taiwan (subcon) ATT6        |

**4. Description of change**

|   |  |   |
|---|--|---|
|   | <b>Old</b>   | <b>New</b>                                    |
| 4.1 Description   | Amkor Taiwan (subcon) ATT3 (T3) as Test site.                    | Amkor Taiwan (subcon) ATT6 (T6) as Test site. |
| 4.2 Anticipated Impact on form,fit, function, quality, reliability or processability? | No impact on Form, Fit, Function, Reliability or Processability. |   |

**5. Reason / motivation for change**

|                      |   |
|----------------------|---|
| 5.1 Motivation       | Following Divisional Commitments towards a continuous improvement philosophy and in agreement with Amkor testing strategy, this transfer guarantees the expansion of test space and consolidates al testers' process in same location, allowing to increase efficiency and production capacity. |
| 5.2 Customer Benefit | SERVICE CONTINUITY  |

**6. Marking of parts / traceability of change**

|                 |                                    |
|-----------------|------------------------------------|
| 6.1 Description | Internal Codification at Test Site |
|-----------------|------------------------------------|

**7. Timing / schedule**

|                                     |              |
|-------------------------------------|--------------|
| 7.1 Date of qualification results   | 2021-09-01   |
| 7.2 Intended start of delivery      | 2021-11-19   |
| 7.3 Qualification sample available? | Upon Request |

**8. Qualification / Validation**

|  |   |            |            |
|--|---|------------|------------|
| 8.1 Description                                    | 13067 Test Transfer Qual Report from T3 toT6 for UQ55_PCI.pdf |            |            |
| 8.2 Qualification report and qualification results | Available (see attachment)                                    | Issue Date | 2021-10-14 |

| 9. Attachments (additional documentations)   |                         |                          |
|--|-------------------------|--------------------------|
| 13067 Public product.pdf<br>13067 Test Transfer Qual Report from T3 toT6 for UQ55_PCI.pdf<br>13067 STM-AMS Analog Test Transfer from Amkor ATT3 to ATT6 - UQ55 Aug21.pdf |                         |                          |
| 10. Affected parts   |                         |                          |
| 10. 1 Current  |                         | 10.2 New (if applicable) |
| 10.1.1 Customer Part No  | 10.1.2 Supplier Part No | 10.1.2 Supplier Part No  |
|  | STBC02AJR               |                          |
|  | STBC02JR                |                          |

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